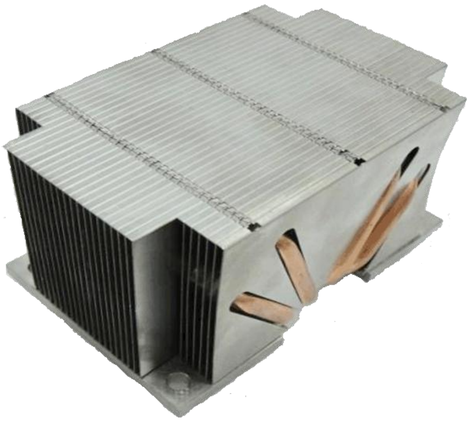
HEL-L60A0-D1-GP



Application

LGA 2011 (Socket R Narrow)

Test result:

	130W
Flow (CFM)	Rca (℃/W)
23	0.2151
	0.2115
	0.2141
26	0.2053
	0.203
	0.2041

Safety

Thermal and Mechanical Spec

Thermal performance for 130W CPU

HSK Assembly Weight: 395 g

CPU Loading: 65 lbf

Component Specifications

Application System	2U Form Factor Passive Solution
Material	Aluminum Fin + Aluminum Base + Heat pipe Diameter 6 × 4
Dimension	70L × 106W × 63.5H mm
Fin	Thick=0.4mm, Pitch=2.2mm, 32 fin
Thermal interface Material	Shin Etsu 7783 (40 × 40 mm)

*All readings are typical values at rated voltage.

*Specifications are subjected to change without notice.